

L Number	Hits	Search Text	DB	Time stamp
-	2045	438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls.	USPAT; EPO; JPO	2003/05/15 23:10
-	956	(438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls.) and bumps	USPAT; EPO; JPO	2003/05/14 21:05
-	36	((438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls.) and bumps) and "thermoplastic resin"	USPAT; EPO; JPO	2003/05/14 21:06
-	4	((438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls.) and bumps) and "thermoplastic resin") and jig	USPAT; EPO; JPO	2003/05/14 21:06
-	1377	438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls. and "flip chip"	USPAT; EPO; JPO	2003/05/15 18:50
-	680	(438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls. and "flip chip") and bump	USPAT; EPO; JPO	2003/05/15 18:51
-	14	((438/613.ccls. 438/411.ccls. 438/461.ccls. 438/611.ccls. 257/737.ccls. and "flip chip") and bump) and "base substrate"	USPAT; EPO; JPO	2003/05/15 18:57
-	0	bumps near "pressed in"	USPAT; EPO; JPO	2003/05/15 18:59
-	0	"electrically connecting the bumps"	USPAT; EPO; JPO	2003/05/15 19:00
-	375	electric\$4 near connect\$3 near bumps	USPAT; EPO; JPO	2003/05/15 19:05
-	0	(electric\$4 near connect\$3 near bumps) same ((one single) adj step)	USPAT; EPO; JPO	2003/05/15 19:10
-	20	(electric\$4 near connect\$3 near bumps) same (sealing adhering)	USPAT; EPO; JPO	2003/05/15 19:10
-	2	("6208525" "5602420").pn.	USPAT	2003/05/15 23:10
-	1	("6208525" "5602420").pn.) and jig	USPAT	2003/05/15 23:10